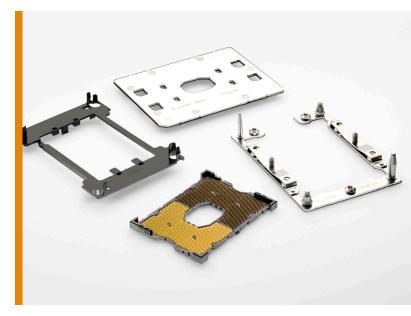
INTRODUCING

LGA 3647 SOCKET & HARDWARE

- Meet future design needs with LGA 3647 sockets and hardware to meet Intel's nextgeneration CPU processors
- Provide higher performance, better system application scaling and better value



TE Connectivity's (TE) LGA 3647 socket and hardware meet the next-generation designs of Intel Corporation's (Intel) new CPU processors for higher performance and better system scaling. LGA 3647 socket is the first to feature a two-piece design that improves issues with warpage and offers better coplanarity and reliability. As one of a limited number of suppliers offering LGA 3647, TE has both socket and hardware parts available to bring you a full solution.

KEY BENEFITS

- Meet future design needs with LGA 3647 sockets and hardware that meet Intel's next-generation CPU processors
- Provide higher performance, better system application scaling and better value with new socket and hardware design
- Offer better coplanarity and reliability with a two-piece design that improves issues with warpage
- Help improve alignment and keep fingers away from the socket contact field with fabric and non-fabric carrier hardware
- Assist in orientation and alignment for the processor heatsink module (PHM) and the spring load force necessary for socket loading with the bolster plate hardware
- Supply mounting points for the bolster plate with back plate hardware

LEARN MORE

LGA 3647 Socket Product Flyer

LGA Socket Landing Page

LGA 3647 Socket Part Listing

LGA 3647 Hardware Part Listing

LGA 3647 Parts List

APPLICATIONS

- Servers
- Storage
- Data centers
- High-performance computing

ELECTRICAL

- Current rating: 0.5 Amps
- Insulation resistance: 500 megohms min. @ 500 VDC

MATERIALS

- Housing: LCP
- Contact: Copper alloy, 30µ" gold plated
- Cap: Thermoplastic

MECHANICAL

• Durability: 30 cycles

STANDARDS & SPECIFICATIONS

• Product specification #108-115115

